



Expand Your Imagination

ThermalFusion 400

www.coolermaster.com

RG-TF4-TGU1-GP



ThermalFusion 400 is a supreme thermal compound that includes high thermal conductivity with low thermal resistance. Its non-curing and non-electrical conductive traits can avoid any short circuit incidence. ThermalFusion 400 is the ultimate solution for thermal dissipation to improve CPU, GPU cooling and other bonding applications.

Features

- High Thermal Conductivity
- Low Thermal Resistance
- Non-Curing
- Non-Corrosive
- Non-Electrical Conductive

Specifications

Color	Gray
Specific Gravity (25°C)	3.5
Thermal Conductivity (W/m-K)	2.89
Volume Resistivity (ohm-cm)	2.0E+10
Thermal Resistance (°C-cm²/W)	0.032
Bond Line Thickness (mm)	0.008
Volatile Content (%)	<0.1
Net Weight (g)	4



Packaging Information

EAN Code	4719512013182
UPC Code	884102002687
Carton Size	485 x 400 x 405 mm
Cuft	2.77
Units / Carton	200

